

2.5V Drive Nch+SBD MOSFET

ES6U41

●Structure

Silicon N-channel MOSFET /
Schottky barrier diode

●Features

- 1) Nch MOSFET and schottky barrier diode- are put in WEMT6 package.
- 2) High-speed switching, Low On-resistance.
- 3) Low voltage drive (2.5V drive).
- 4) Built-in Low V_F schottky barrier diode.

●Applications

Switching

●Package specifications

Type	Package	Taping
	Code	T2R
	Basic ordering unit (pieces)	8000
ES6U41		○

●Absolute maximum ratings (Ta=25°C)

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Parameter	Symbol	Limits	Unit
Drain-source voltage	V _{DSS}	30	V
Gate-source voltage	V _{GSS}	±12	V
Drain current	Continuous	I _D	A
	Pulsed	I _{DP} *1	A
Source current (Body diode)	Continuous	I _S	A
	Pulsed	I _{SP} *1	A
Channel temperature	T _{ch}	150	°C
Power dissipation	P _D *2	0.7	W / ELEMENT

*1 Pw≤10μs, Duty cycle≤1%

*2 Mounted on a ceramic board

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Parameter	Symbol	Limits	Unit
Repetitive peak reverse voltage	V _{RM}	25	V
Reverse voltage	V _R	20	V
Forward current	I _F	0.5	A
Forward current surge peak	I _{FSM} *1	2.0	A
Junction temperature	T _j	150	°C
Power dissipation	P _D *2	0.5	W / ELEMENT

*1 60Hz • 1cycle

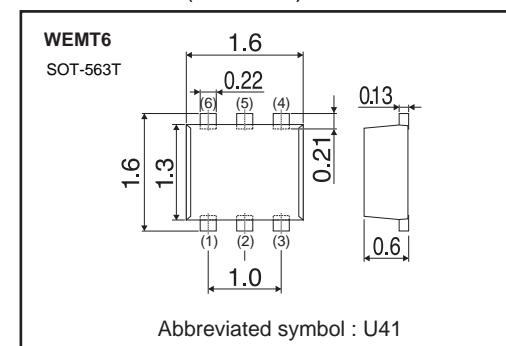
*2 Mounted on ceramic board

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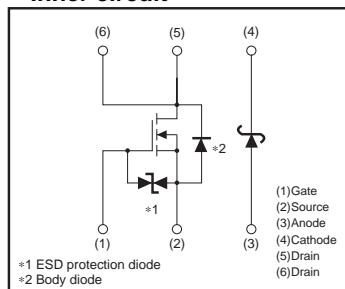
Parameter	Symbol	Limits	Unit
Power dissipation	P _D *	0.8	W / TOTAL
Range of storage temperature	T _{stg}	-55 to +150	°C

* Mounted on a ceramic board

●Dimensions (Unit : mm)



●Inner circuit



●Electrical characteristics

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Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 12V, V_{DS} = 0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 1mA, V_{GS} = 0V$
Zero gate voltage drain current	I_{DSS}	—	—	1	μA	$V_{DS} = 30V, V_{GS} = 0V$
Gate threshold voltage	$V_{GS(\text{th})}$	0.5	—	1.5	V	$V_{DS} = 10V, I_D = 1mA$
Static drain-source on-state resistance	$R_{DS(\text{on})}^*$	—	170	240	$m\Omega$	$I_D = 1.5A, V_{GS} = 4.5V$
		—	180	250	$m\Omega$	$I_D = 1.5A, V_{GS} = 4V$
		—	240	340	$m\Omega$	$I_D = 1.5A, V_{GS} = 2.5V$
Forward transfer admittance	$ Y_{fs} ^*$	1.5	—	—	S	$V_{DS} = 10V, I_D = 1.5A$
Input capacitance	C_{iss}	—	80	—	pF	$V_{DS} = 10V$
Output capacitance	C_{oss}	—	14	—	pF	$V_{GS} = 0V$
Reverse transfer capacitance	C_{rss}	—	12	—	pF	$f = 1MHz$
Turn-on delay time	$t_d(\text{on})^*$	—	7	—	ns	$V_{DD} = 15V$
Rise time	t_r^*	—	9	—	ns	$I_D = 0.75A$
Turn-off delay time	$t_d(\text{off})^*$	—	15	—	ns	$V_{GS} = 4.5V$
Fall time	t_f^*	—	6	—	ns	$R_L = 20\Omega$
Total gate charge	Q_g^*	—	1.6	2.2	nC	$V_{DD} = 15V, V_{GS} = 4.5V$
Gate-source charge	Q_{gs}	—	0.5	—	nC	$I_D = 1.5A, R_L = 10\Omega$
Gate-drain charge	Q_{gd}	—	0.3	—	nC	$R_G = 10\Omega$

*Pulsed

<Body diode characteristics (Source-drain)>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_{SD}	—	—	1.2	V	$I_S = 0.75A, V_{GS} = 0V$

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Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_F	—	—	0.36	V	$I_F = 0.1A$
		—	—	0.52	V	$I_F = 0.5A$
Reverse current	I_R	—	—	100	μA	$V_R = 20V$

●Electrical characteristics curves
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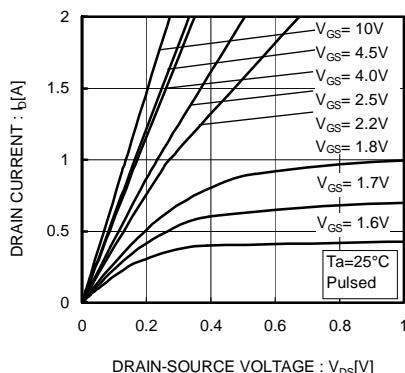


Fig.1 Typical Output Characteristics(I)

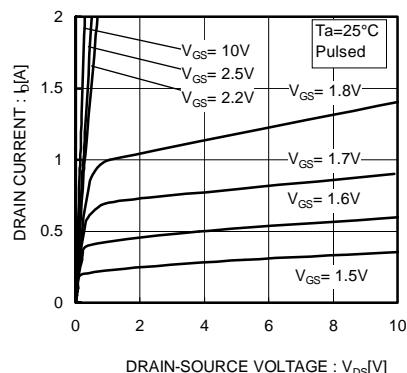


Fig.2 Typical Output Characteristics(II)

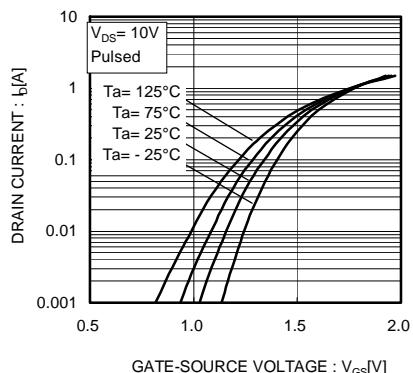


Fig.3 Typical Transfer Characteristics

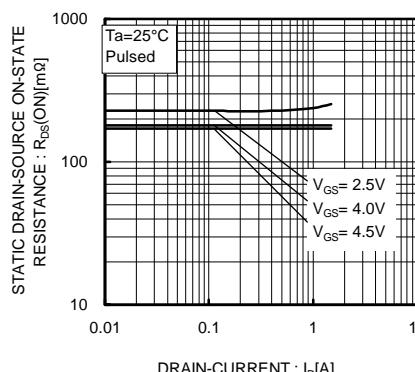


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current(I)

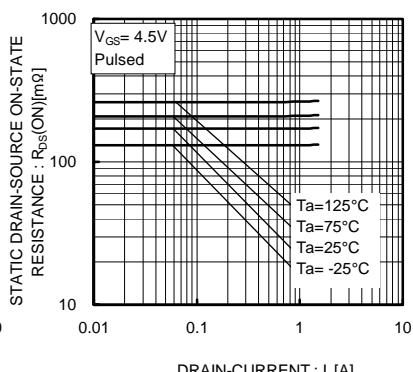


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(II)

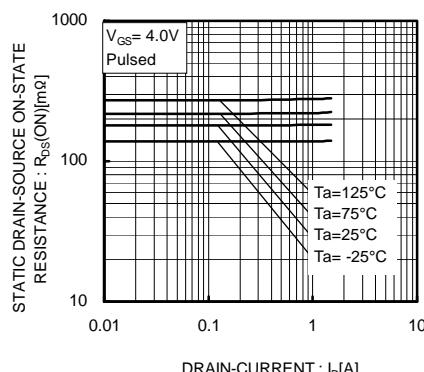


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(III)

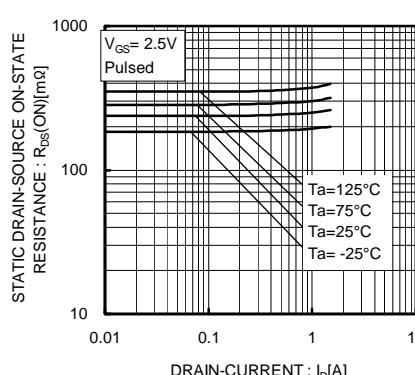


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current(IV)

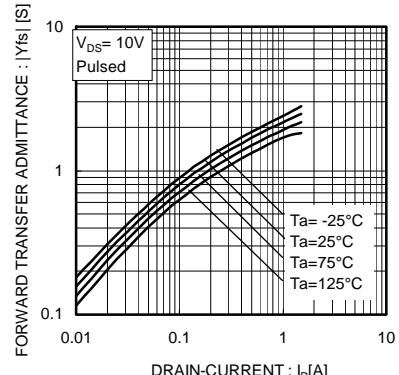


Fig.8 Forward Transfer Admittance vs. Drain Current

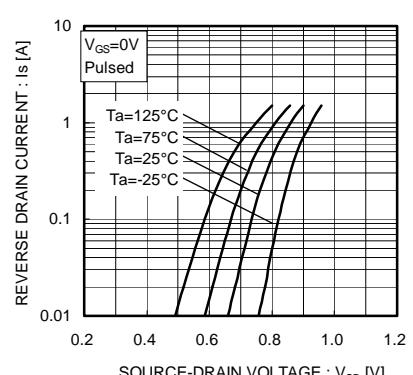


Fig.9 Reverse Drain Current vs. Sourse-Drain Voltage

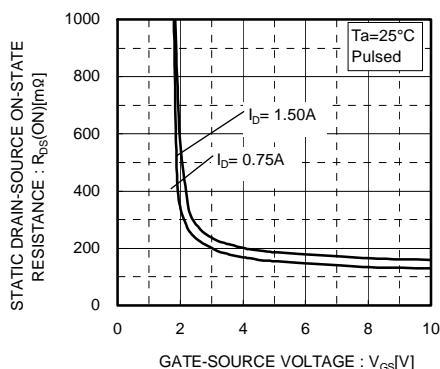


Fig.10 Static Drain-Source On-State
Resistance vs. Gate Source Voltage

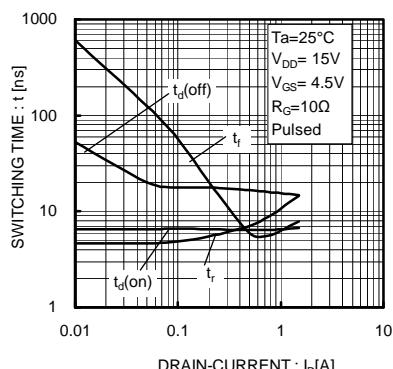


Fig.11 Switching Characteristics

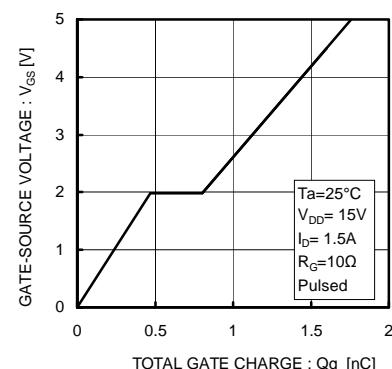


Fig.12 Dynamic Input Characteristics

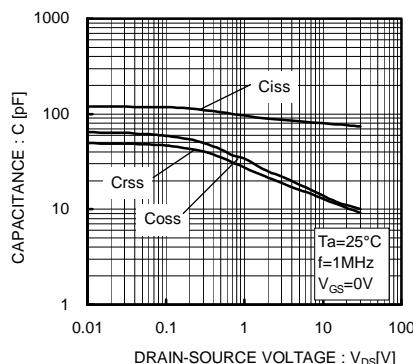


Fig.13 Typical Capacitance
vs. Drain-Source Voltage

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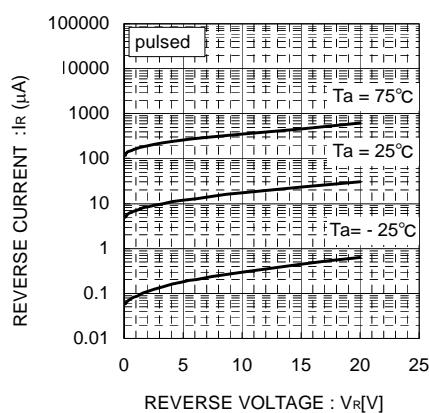


Fig.1 Reverse Current vs. Reverse Voltage

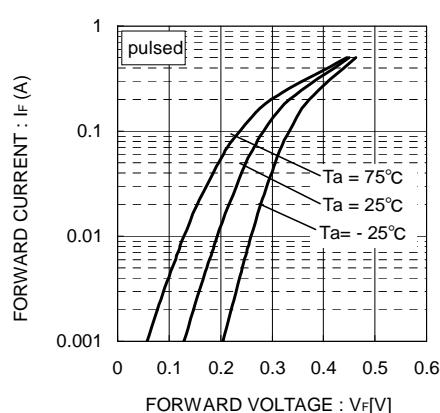


Fig.2 Forward Current vs. Forward Voltage

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